



SOT813-4

plastic thermal enhanced very thin quad flat package; no leads; 72 terminals, 0.5 mm pitch, 10 mm x 10 mm x 0.85 mm body

11 February 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN72
Package type industry code	HVQFN72
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	26-07-2012
Manufacturer package code	SOT813

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	9.9	10	10.1	mm
package width	9.9	10	10.1	mm
seated height	0.8	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	72	-	



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2 Package outline

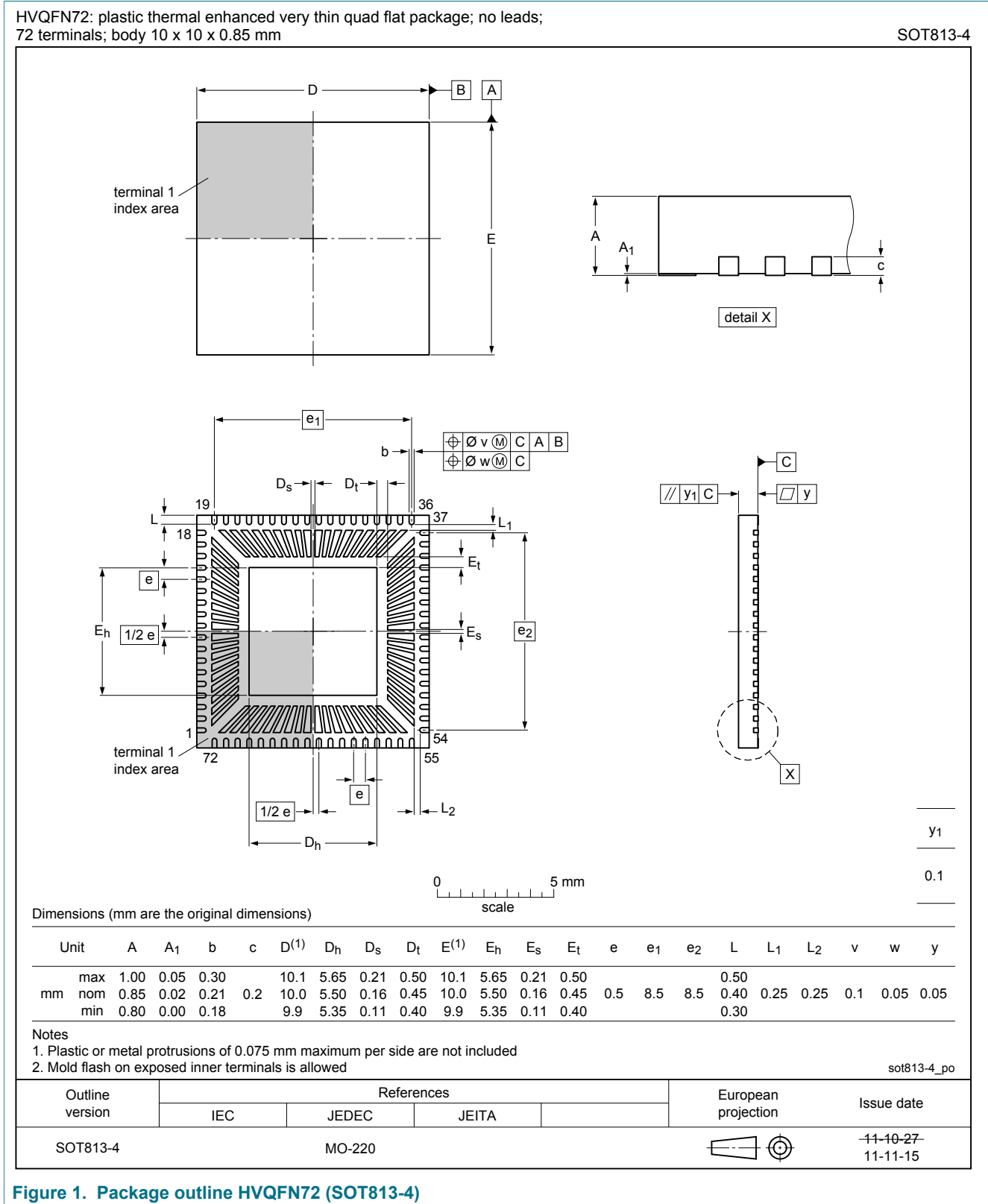


Figure 1. Package outline HVQFN72 (SOT813-4)

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3 Soldering

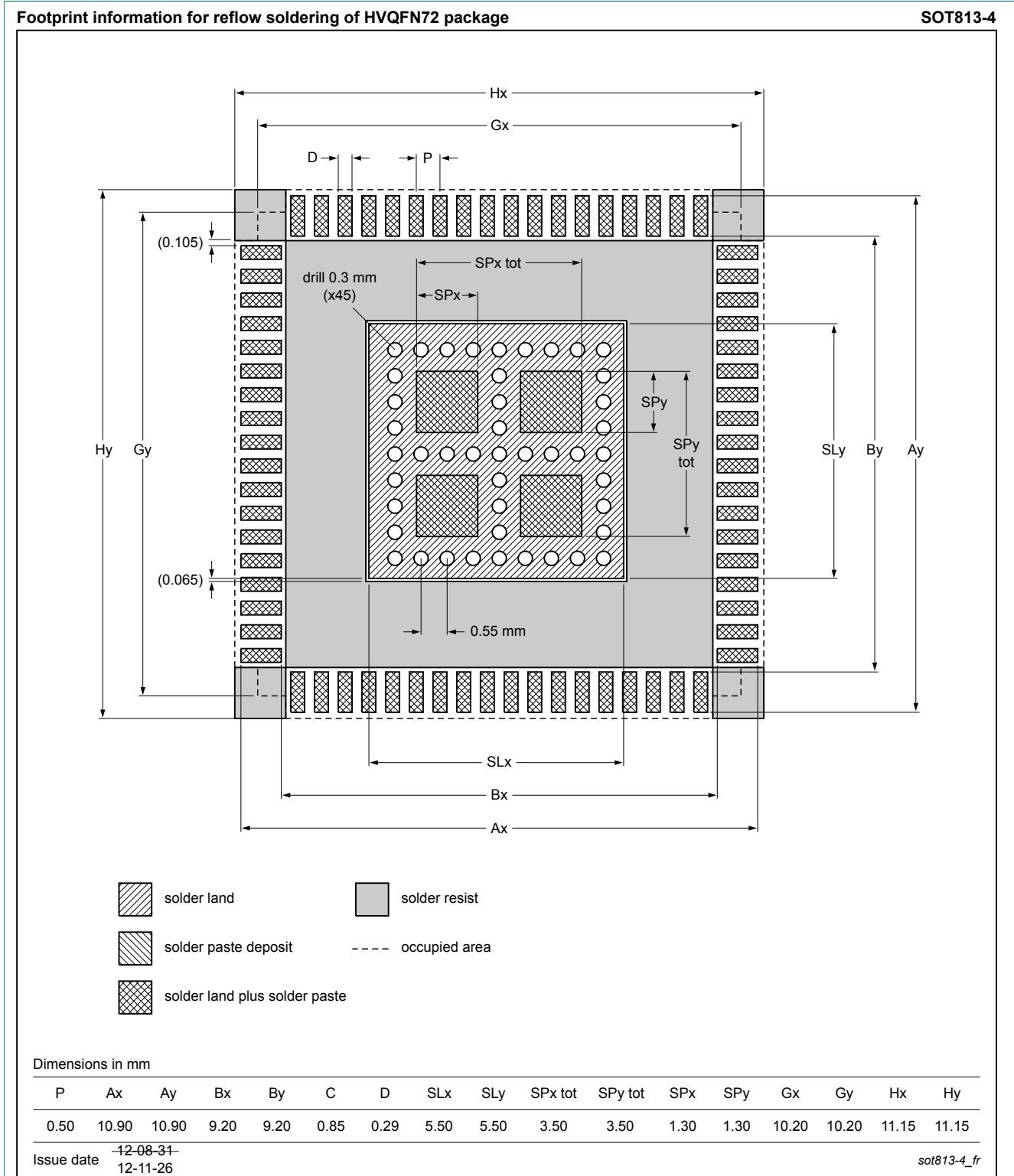


Figure 2. Reflow soldering footprint for HVQFN72 (SOT813-4)

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4 Legal information

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